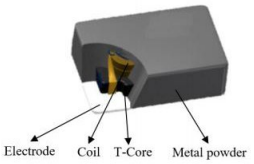
SMD POWER INDUCTOR



FEATURES	■ Low profile ■ Low DCR ■ Large Current Adaptable ■ High Frequency(up to 3MHz)	■ SMT 貼片式 ■ 低高度 ■ 耐大電流 ■ 低阻抗. ■ 高頻率 (最高至 3MHz)

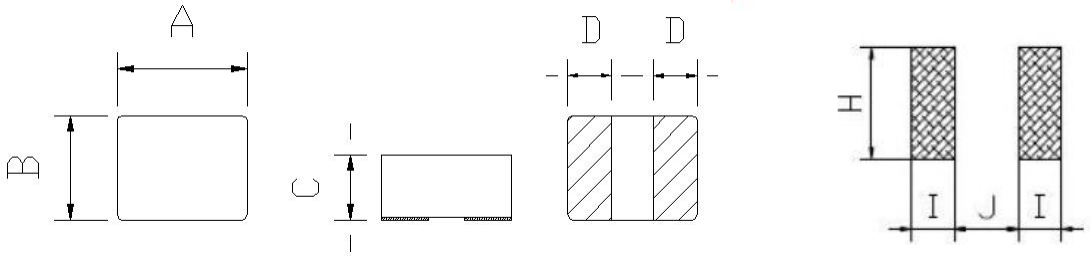
APPLICATIONS	■ DC/DC converter for CPU in Notebook PC ■ Battery powered devices ■ . Cellular phones LCD displays, HDDs, DVCs, DSCs, PDA etc. ■ Thin type on-board power supply module	■ 用於筆記本電腦處理器的 DC/DC 轉換設備 ■ 電源,電池設備. ■ 適用於手機液晶屏顯示,HDD, DVC, DSC, PDA 等 ■ 薄型車載電源模組

PRODUCT IDENTIFICATION

FEMP	201610	H	-	2R2	M
(1)	(2)	(3)		(3)	(5)

(1) PRODUCT NAME
(2) DIMENSION
(3) TYPE
(4) INDUCTANCE
(5) TOLERANCE

CONFIGURATIONS & DIMENSIONS（unit in mm）



Type	A	B	C	D	H	I	J
FEMP252012	2.50 ±0.2	2.00 ±0.2	1.20 Max	0.90 REF	2.10 REF	0.95 REF	0.70 REF
FEMP322520	3.20 ±0.2	2.50 ±0.2	2.00 Max	1.15 REF	0.9 REF	1.175 REF	0.90 REF

Specification

ELECTRICAL CHARACTERISTICS FOR FEMP252012H SERIES					
Part Number	Inductance (uH)±20%	Test Condition (MHz)	DCR (mΩ) MAX	I rms (A) MAX	I sat (A) MAX
FEMP252012H -R10M	0.10	1MHz/1V	10.0	10.5	12.5
FEMP252012H -R15M	0.15		11.0	10.0	12.0
FEMP252012H -R22M	0.22		14.0	7.60	9.00
FEMP252012H -R24M	0.24		15.0	7.50	8.80
FEMP252012H -R33M	0.33		17.0	6.40	7.80
FEMP252012H -R47M	0.47		19.0	6.00	7.00
FEMP252012H -R68M	0.68		23.0	5.50	6.00
FEMP252012H -R82M	0.82		24.0	5.30	5.80
FEMP252012H -1R0M	1.00		42.0	3.60	5.00
FEMP252012H -1R5M	1.50		50.0	3.20	4.10
FEMP252012H -2R2M	2.20		65.0	2.70	3.30
FEMP252012H -3R3M	3.30		97.0	1.80	2.70
FEMP252012H -4R7M	4.70		170.0	1.50	2.10
FEMP252012H -6R8M	6.80		270.0	1.40	1.70
FEMP252012H -100M	10.0		400.0	1.05	1.45

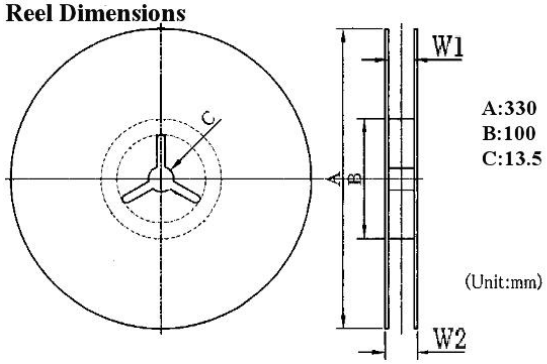
ELECTRICAL CHARACTERISTICS FOR FEMP322520H SERIES					
Part Number	Inductance (uH)±20%	Test Condition (MHz)	DCR (mΩ) MAX	I rms (A) MAX	I sat (A) MAX
FEMP322520H-R33M	0.33	1MHz/1V	9.00	9.0	14.0
FEMP322520H-R47M	0.47		10.5	8.5	13.0
FEMP322520H-R68M	0.68		14.5	8.0	11.0
FEMP322520H-1R0M	1.00		17.5	7.5	8.3
FEMP322520H-1R5M	1.50		25.0	6.0	6.0
FEMP322520H-2R2M	2.20		43.0	4.8	5.5
FEMP322520H-3R3M	3.30		60.0	4.0	3.5
FEMP322520H-4R7M	4.70		94.0	3.0	3.0

Note:

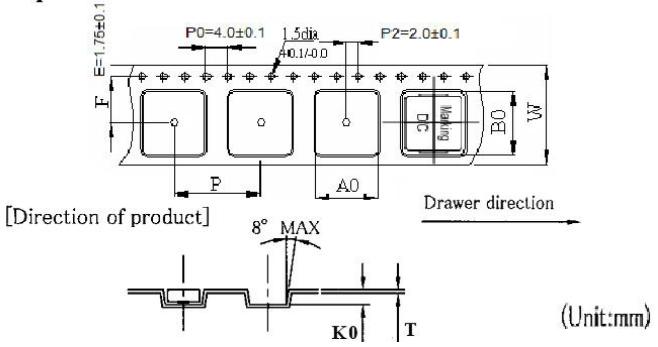
1. Tolerance of Inductance: N=±30% ,M=±20%.
2. All test data is referenced to 25℃ ambient.
3. Inductance is measured at 100KHz. 25℃ ambient.
4. Operating Temperature Range-50℃ to +125℃.
5. DC current (Irms) (A) that will cause an approximate △T of 40℃.
6. DC current (Isat) (A) that will cause Lo to drop approximately 30%.
7. The part Temperature (ambient + temp rise) should not exceed 125℃ under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature Part temperature should be verified in the end application.

Taping Dimension for FEMP H series

Reel Dimensions



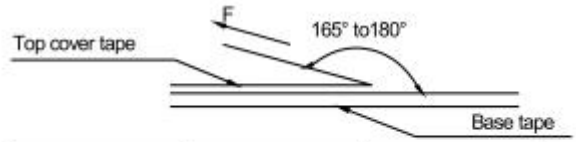
Tape Dimensions



TYPE	A	B	C	W1	W2	Q' TY (PCS)
FEMP252012H	178.0±2.0	60.0±0.5	13.0±0.5	9.0±0.5	11.0±0.5	3000
FEMP322520H	330.0±2.0	100.0±0.5	13.5±0.5	9.5±0.5	13.5±0.5	3000

TYPE	W	A0	B0	K0	P	F	T
FEMP252012H	8.0±0.1	2.4±0.1	2.85±0.1	1.4±0.1	4.0±0.1	3.5±0.1	0.23±0.1
FEMP322520H	8.0±0.1	2.9±0.1	3.5±0.1	2.2±0.1	4.0±0.1	3.5±0.1	0.28±0.05

- **Tearing Off Force**



Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

The force tearing off cover 10 to 130 grams (0.1N to 1.3N) in the arrow direction under the following conditions.

- **Storage conditions/Note things**

(1) Storage temperature and humidity conditions :

1. Product packing with Carrier tape: +5℃~+40℃ and less than 60% RH.
2. Product alone: -20℃~+60℃ and less than 60% RH.

(2) Products should be used within 6 months.

(3) The packaging material should be kept where no chlorine or sulfur exists in the air.

(4) Do not touch the electrodes (soldering terminals) with fingers as this may lead to deterioration of solder ability.

(5) The use of tweezers or vacuum pick-ups is strongly recommended for individual components.

(6) Bulk handling should ensure that abrasion and mechanical shock are minimized